

11th IEEE European Test Symposium

Hilton Hotel, Southampton, United Kingdom
May 21-25, 2006
<http://www.ieee-ets.org>



Vendor Sessions – Call for Submissions

The IEEE European Test Symposium (ETS) is Europe's premier forum dedicated to presenting and discussing scientific results, emerging ideas, practical applications, hot topics, and new trends in the area of electronic-based circuit and system testing. In 2006, ETS will take place in Southampton, the historic port on the south coast of England. ETS'06 is being organized by the University of Southampton and sponsored by the Test Technology Technical Council (TTTC) of the IEEE Computer Society.

ETS'06 is offering commercial vendors the opportunity to give technical presentations in a track parallel to the technical sessions. These presentations will be listed in the symposium program along with the technical sessions, and should be targeted to the ETS technical audience. The vendor presentation sessions will differ from standard ETS presentations in that product names and logos may be mentioned explicitly. Typical content could include product descriptions, case studies, best practices, and testimonials.

Presentation opportunities of 30-minute duration are available on a first-come first-served basis but priority will be given to those companies that are also sponsors of ETS'06 – see below. Attendance at the sessions will be open to all symposium attendees, and vendor representatives will be able to hand out literature at the session.

Review Procedure

Proposals for the vendor session should be technical or application focused rather than overtly sales-and-marketing focused. Proposals reviews will be based on the technical content and relevance to ETS'06 audience and topics. The areas of interest of ETS'06 include (but are not limited to) the following topics:

- Analog, Mixed-Signal, RF Test
- ATE Hardware and Software
- Automatic Test Generation
- Board and System Test
- Built-In Self Test (BIST)
- Current-Based Test
- Defect and Fault Tolerance
- Delay and Performance Test
- Design for Test(ability) (DfT)
- Design Verification and Validation
- Diagnosis and Debug
- (Embedded) System Test
- Failure Analysis
- Fault Modeling and Simulation
- High-Level DfT and TPG
- High-Speed IO/Interconnect Test
- Memory Test and Repair
- MEMS and Nanotechnology Test
- Microprocessor Test
- Nanometer Technologies Test
- On-Line and Off-Line Test
- Power Issues in Test
- Self-Repair Methodologies
- Signal Integrity Test
- Standards in Testing
- System-in-Package (SiP) Test
- System-on-Chip (SoC) Test
- Test Data Compression
- Test of Reconfigurable Systems
- Test Quality and Reliability
- Test(ability) Synthesis
- Thermal Test
- Yield Analysis and Enhancement

Submissions

A submission to the ETS'06 Vendor Sessions can be an abstract, extended abstract, or full paper (max. six pages). Submission of a full paper is preferred, but not required. Proposals should be submitted via the ETS'06 web site; detailed submission instructions can also be found there (go to <http://www.ieee-ets.org>, follow the link to ETS'06, and then select Paper Submission under Author Instructions). Key dates for submissions:

- Submission deadline : **December 9, 2005**
- Notification of acceptance : **February 11, 2006**
- Camera-ready manuscript : **March 11, 2006**

ETS'06 Industrial Sponsorship

Every year, ETS is sponsored by several companies. The sponsorship money is used to reduce the registration fees and hence make the event more accessible to all its attendees. In return, the sponsoring companies are allowed to make publicity in various ways. ETS has defined four different sponsor grades (named Bronze, Silver, Gold, and Platinum), each with different money amounts and different publicity paths. To find out more, contact Ben Bennetts, details below

More Information

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Visit the ETS web page at: <http://www.ieee-ets.org>

